

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5817158

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| DA MI CHOI | 11/06/2019 |
| JEONG SEOK LEE | 11/06/2019 |
| JIN HYUNG SHIM | 11/06/2019 |
| WON-SOO YUN | 11/06/2019 |
| JUNG HO LEE | 11/11/2019 |
| RECEIVING PARTY DATA | |
| Name: | T&R BIOFAB CO., LTD. |
| Street Address: | 540HO, 237, SANGIDAEHAK-RO, GYEONGGI-DO |
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| State/Country: | KOREA, REPUBLIC OF |
| Postal Code: | 15073 |
| Name: | THE CATHOLIC UNIVERSITY OF KOREA INDUSTRY-ACADEMIC COOPERATION FOUNDATION |
| Street Address: | 222, BANPO-DAERO, SEOCHO-GU |
| City: | SEOUL |
| State/Country: | KOREA, REPUBLIC OF |
| Postal Code: | 06591 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 29712991 |
| CORRESPONDENCE DATA | |
| Fax Number: | (240)366-1263 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
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|--|----------------|
| NAME OF SUBMITTER: | MINCHUL YANG |
| SIGNATURE: | /minchul yang/ |
| DATE SIGNED: | 11/13/2019 |
| Total Attachments: 1 source=assn190075#page1.tif | |

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

[Insert ASSIGNEE's Name(s) Address(es)]

T&R Biofab Co., Ltd.
540ho, 237, Sangidaehak-ro, Gyeonggi-do, Siheung-si, 15073, Republic of Korea

THE CATHOLIC UNIVERSITY OF KOREA INDUSTRY-ACADEMIC COOPERATION FOUNDATION
222, Banpo-daero, Seocho-gu, Seoul 06591, Republic of Korea

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest, including the right to sue for past infringement, if any, and all rights pursuant to 35 U.S.C. §154, to the invention entitled

[Title of Invention]

IMPLANT FOR RECONSTRUCTING NIPPLE

[*if the assignment is being filed after the filing of the application, this section must be completed]

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

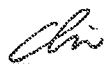
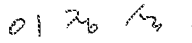
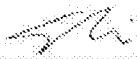
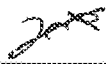
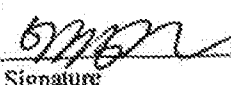
filed on 13-NOV-2019, Serial No. 29712991
(STIP Law Group LLC is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof, and any other application claiming priority thereto, for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

| | | |
|-----------------|--|---------------|
| CHOI, Da Mi |  | Nov 06 / 2019 |
| Name | Signature | Date |
| LEE, Jeong Seok |  | Nov 06 / 2019 |
| Name | Signature | Date |
| SHIM, Jin Hyung |  | Nov 06 / 2019 |
| Name | Signature | Date |
| YUN, Won-Soo |  | Nov 06 / 2019 |
| Name | Signature | Date |
| LEE, Jung Ho |  | Nov-11-2019 |
| Name | Signature | Date |

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